SN74AHCT1G02 SINGLE 2-INPUT POSITIVE-NOR GATE

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- Operating Range of 4.5 V to 5.5 V
- Max t_{pd} of 6.5 ns at 5 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±8-mA Output Drive at 5 V
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE

description/ordering information

This device contains a single 2-input NOR gate that performs the Boolean function $Y = \overline{A} \bullet \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

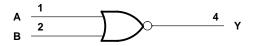
TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
	SOT (SOT-23) – DBV	Reel of 3000	SN74AHCT1G02DBVR	B02
–40°C to 85°C	301 (301- <u>2</u> 3) – DBV	Reel of 250	SN74AHCT1G02DBVT	D02_
	COT (CC 70) DOK	Reel of 3000	SN74AHCT1G02DCKR	BB
	SOT (SC-70) – DCK	Reel of 250	SN74AHCT1G02DCKT	DD_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Х	L
Х	Н	L
L	L	Н

logic diagram (positive logic)





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[‡]The actual top-side marking has one additional character that designates the assembly/test site.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Note 1)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
٧ _I	Input voltage	0	5.5	V
٧o	Output voltage	0	VCC	V
Іон	High-level output current		-8	mA
l _{OL}	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	T _A = 25°C			MIN	MAX	UNIT
PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	IVIIIN	WAX	UNII
Vou	$I_{OH} = -50 \mu A$	4.5 V	4.4	4.5		4.4		V
VOH	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1		0.1	V
	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.44	
lį	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			1		10	μΑ
Δl _{CC} ‡	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			1.35		1.5	mA
C _i	$V_I = V_{CC}$ or GND	5 V		4	10		10	pF

[‡] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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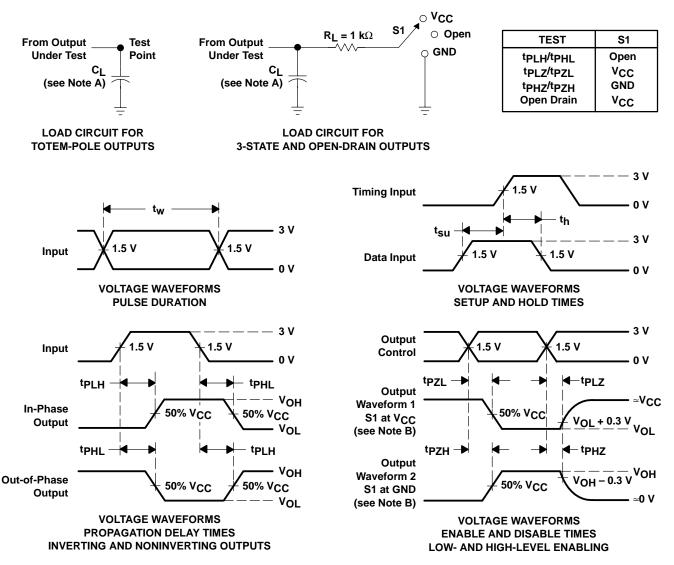
switching characteristics over recommended operating free-air temperature range, $V_{CC}=5~V\pm0.5~V$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	- I	T _A = 25°C			MIN MAX	UNIT	
PARAMETER	(INPUT)	(OUTPUT)		MIN	TYP	MAX	IVIIIV	IVIAA	UNIT
^t PLH	A or B	V	C: -15 pF		2.4	5.5	1	6.5	no
t _{PHL}	AUIB	ī	$C_L = 15 pF$		3.5	5.5	1	6.5	ns
^t PLH	A or B	Y	C: 50 pF		3.4	7.5	1	8.5	no
^t PHL	AUB		Y C _L = 50 pF		4.5	7.5	1	8.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER		ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	17	pF

PARAMETER MEASUREMENT INFORMATION



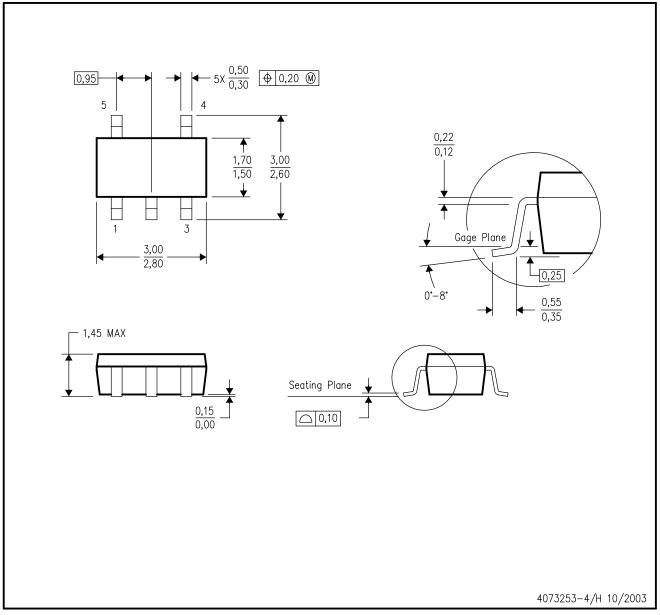
- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns. $t_f \leq 3$ ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



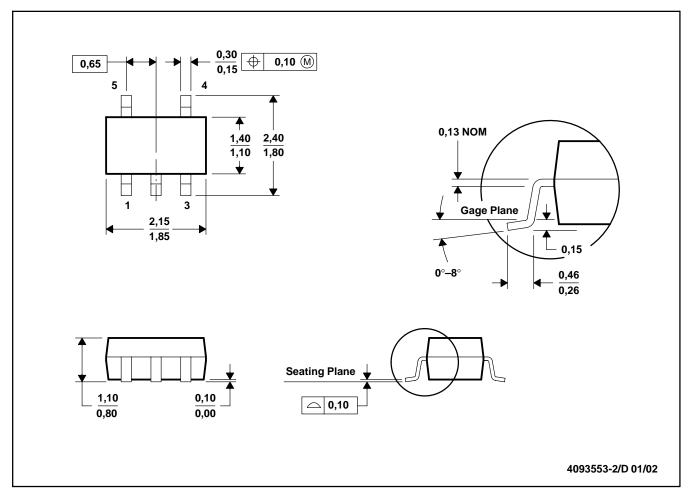
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- C. Body dimensions do not include mold fla D. Falls within JEDEC MO—178 Variation AA. Body dimensions do not include mold flash or protrusion.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-203

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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